IPC ASSOCIATION ELECTRONICS	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					rials and M	ials and Mfg Information			
Supplier	Information														
Company name* Company uniqu				que ID			Unique ID Authority				Response Date*				
onsemi											2023-06	2023-06-08			
Contact Name			Title - Contact]	Phone - Contact*				Email - Contact*				
Product-E	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized	l Representative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-E	Cnv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	Date Version Manufacturing Site			Weight*	UOM	Unit Type		
		LE24LA322CSTL2- WLP I2C EEPROI		M(32K)		2023-06-08 PHM			1.42	mg	Each				
Aanufa	cturing Proccess Informa	ation													
	Terminal Plating / Grid Array Material			Cerminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Temperature Max Time at I		re Max Time at Peal	k Tempera	ture Nu	mber of Reflow Cyc	les		
SnAgCu			CU Alloy 1			260	0 C 30		seconds 3						
omments															
vel 1 - ma	aximum time at peak temperat	ure during sol	ldering is 10-3	0 seconds						<u>-</u>			<u> </u>	·	
or more i	nformation regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Sta											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Backside Protection Film	0.06	mg	Supplier	Epoxy resins	129915-35-1		0.06	mg
Die	1.02	mg	Supplier	Silicon (Si)	7440-21-3		1.0137	mg
			Supplier	Polyimide	Proprietary Data		0.0063	mg
Electrode	0.14	mg	Supplier	Titanium (Ti)	7440-32-6		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.1397	mg
Insulating Layer	0.01	mg		Polyimide	proprietary data		0.01	mg
Protection coat	0.1	mg	Supplier	Epoxy resins	129915-35-1		0.1	mg
Solder Ball	0.09	mg	Supplier	Silver (Ag)	7440-22-4		0.0027	mg
			Supplier	Tin (Sn)	7440-31-5		0.0869	mg
			Supplier	Copper (Cu)	7440-50-8		0.0005	mg